

PRODUCT NO.
73725

PRODUCT NUMBER CODE

73725-X X X X LF

HOUSING COLOR OPTION
0-WHITE
1-BLACK

SENSOR CONTACT OPTION
0-WITH SENSOR CONTACT
1-WITHOUT SENSOR CONTACT

SHIELD PLATING OPTION
1- 1.25μm MINIMUM NICKEL UNDERPLATE & 2.5μm MINIMUM BRIGHT TIN OVER ALL AREA. (HOLD DOWN STYLE "A")
2- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL; 2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY.(HOLD DOWN STYLE "B")
3- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL; 2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY.(HOLD DOWN STYLE "A")
4- 1.25μm MINIMUM NICKEL UNDERPLATED & 2.5μm MINIMUM BRIGHT TIN OVER ALL AREA. (HOLD DOWN STYLE "B")
5- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL; 2.5μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY (HOLD DOWN STYLE "C")
6- 1.25μm MINIMUM NICKEL ONLY. (HOLD DOWN STYLE "A")
7- 1.25μm MINIMUM NICKEL UNDERPLATED & 2.5 μm MINIMUM MATTE TIN PLATED OVER ALL. (HOLD DOWN STYLE "A")
8- 1.25μm MINIMUM NICKEL UNDERPLATED & 2.5 μm MINIMUM MATTE TIN PLATED ALL AREA. (HOLD DOWN STYLE "B")
9- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL; 2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY (HOLD DOWN STYLE "D")
S- 1.25μm MINIMUM NICKEL ONLY.(HOLD DOWN STYLE "A"). HIGH PERFORMANCE MATERIAL FOR 12,000 DURABILITY CYCLES
A- 1.25μm MINIMUM NICKEL PLATED OVER ALL 2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY (HOLD DOWN STYLE "F")
B- 1.25μm MINIMUM NICKEL PLATED OVER ALL 2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY (HOLD DOWN STYLE "F")

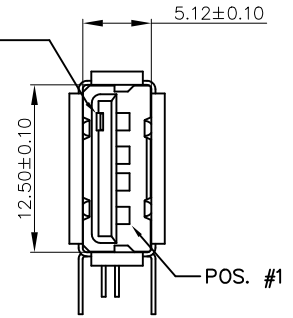
TERMINAL OPTION
50u" NI UNDERPLATE; 30u" GXT CONTACT AREA,100u" TIN TAIL AREA;
0- DIM "A": 2.29 (TERMINAL TAIL LENGTH);
1- DIM "A": 3.71 (TERMINAL TAIL LENGTH);

LEAD FREE OPTION
SEE NOTE 9

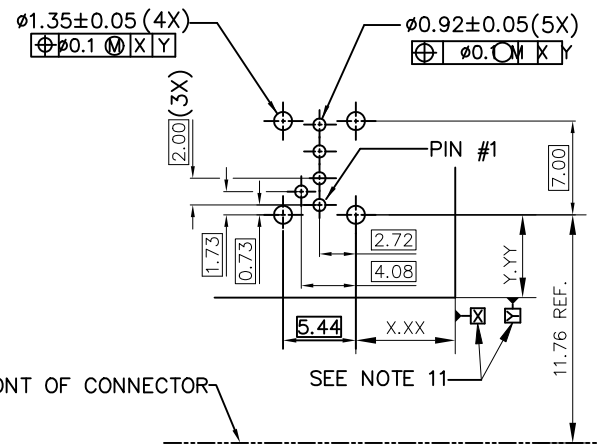
PACKAGING OPTION
B - TUBE
R - TAPE&REEL



SENSOR CONTACT

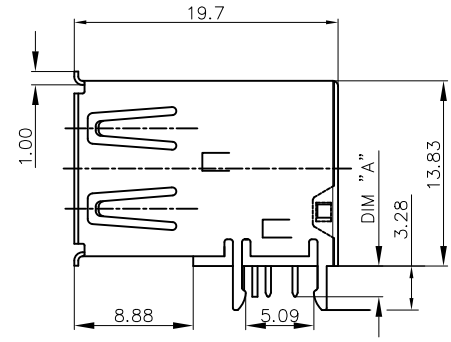


WITH SENSOR CONTACT



FRONT OF CONNECTOR

PC BOARD MOUNTING DIMENSIONS FOR 5 PIN



FOR 73725-X0X0B
HOLD DOWN STYLE "A"

NOTES:

- MATERIAL:
CONTACTS: COPPER ALLOY
SHIELD: COPPER ALLOY
HOUSING: UL 94V-0 THERMOPLASTIC, COLOR: SEE PRODUCT CODE
- PLATING:
CONTACTS: GOLD FLASH OVER PALLADIUM NICKEL (0.76μm MINIMUM) IN CONTACT AREA; 2.5 μm TIN MINIMUM IN SOLDER TAIL AREA.
SHIELD: 1.27 μm MINIMUM NICKEL UNDERPLATE OVER ALL SURFACES.
(THE PLATING MEASURE POINT ON THE SHIELD HOLD DOWN AREA ONLY).
- DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER
- RECOMMENDED PCB BOARD THICKNESS IS 1.00 ~ 1.60mm EXCEPT 73725-1191BLF; 73725-1191BLF CAN BE USED FOR THE PCB BOARD THICKNESS 2.30 ~ 2.65mm.
- MAXIMUM PANEL THICKNESS TO BE 2.67mm IF MOUNTED BEHIND PANEL
- METAL SHELL SLIVER 0.20 MAX.
- NI PLATING DOES NOT COMPLY WITH THE USB STANDARDS (TO BE CONTINUED)

mat'l. code				surface123/tolerance			projection		product family		
				ISO 1302	ISO 406	ISO 1101			HPL 511 USB 2.0		
ltr	ecn no	dr	date	tolerances unless otherwise specified			mm		title		
AJ	ELX-N-27708	LZ	2017/08/15	angles	linear				USB UP-RIGHT RECEPT		
AD	ELX-N-012006	A.ZH	06/25/2012	0°±2'			scale 1:1				
AE	ELX-N-13463	A.ZH	11/14/2012	dr	PAMP	5/20/97			dwg no		
AF	ELX-N-14592	J.HAN	06/10/2013	engr	R Y LIU	5/20/97			sheet 1 of 4		
AG	ELX-N-21594	LQ	08/04/2015	chr	R Y LIU	5/20/97			73725		
AH	ELX-N-21919	LQ	08/04/2015	app	JENN TSAO	5/20/97			type Product Customer Drawing		
sheet	revision										
index	sheet										

PRODUCT NO.
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(CONTINUED)

8. P/N'S WITH SUFFIX "LF" ARE LEAD FREE P/N'S

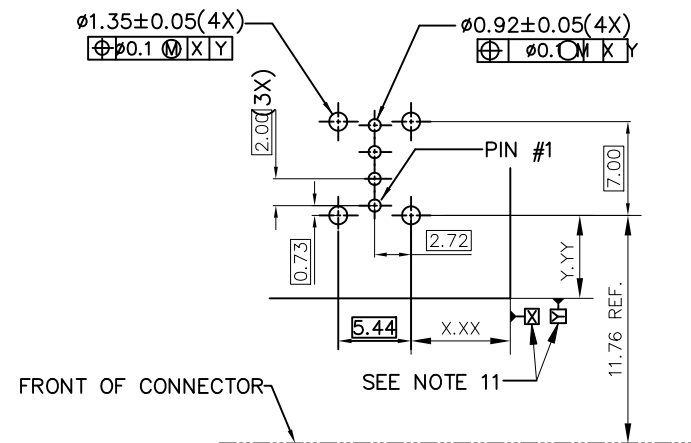
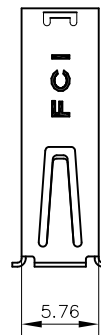
FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008

FOR THE PRODUCTS WITH THE METAL SHELL PLATING NICKEL AND MATTE SN CAN WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW PROCESS; FOR THE PRODUCTS WITH METAL SHELL PLATING BRIGHT SN OR SEMI-BRIGHT SN CAN'T WITHSTAND REFLOW AND JUST CAN WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN WAVE SOLDERING PROCESS.

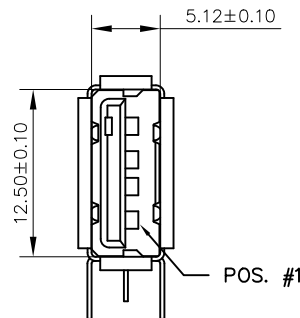
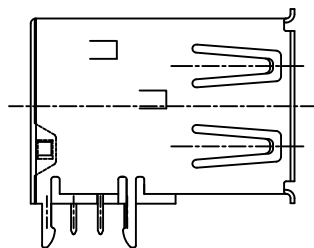
FOR ALL LEAD FREE P/N'S, WITH SUFFIX LF.

12. THE PRODUCT CAN BE USED FOR PIP PROCESS

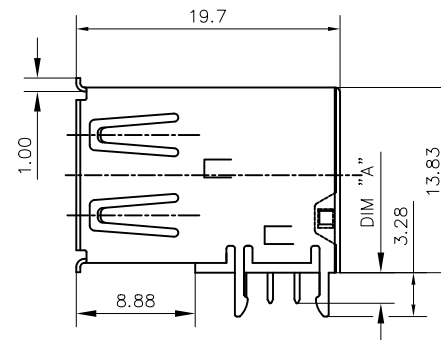
13. DATUM OF CUSTOMER'S PCB LAYOUT.



PC BOARD MOUNTING DIMENSIONS FOR 4 PIN

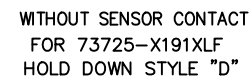
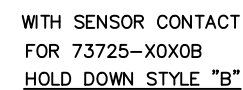
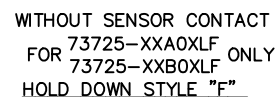
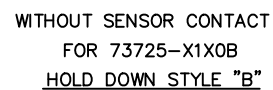


WITHOUT SENSOR CONTACT



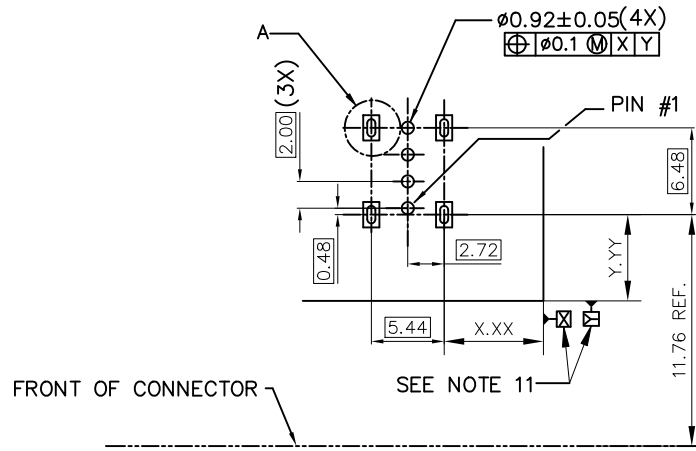
FOR 73725-X1X0B
HOLD DOWN STYLE "A"

mat'l. code				surface ¹²³ /tolerance			projection		product family					
				ISO 1302 ✓ ISO 406 ISO 1101					HPL 511 USB 2.0					
ltr	ecn	no	dr	date			tolerances unless otherwise specified		title					
AJ				angles		linear	.0±.30			USB UP-RIGHT RECEPT				
							.00±.20							
				0°±2°			.000±.10	scale 1:1						
				dr		PAMP	5/20/97			dwg no		sheet2 of 4		size
				eng		R Y LIU	5/20/97			73725		A3		
				chr		R Y LIU	5/20/97							
				app		JENN TSAO	5/20/97			type Product Customer Drawing				
sheet index		revision sheet												

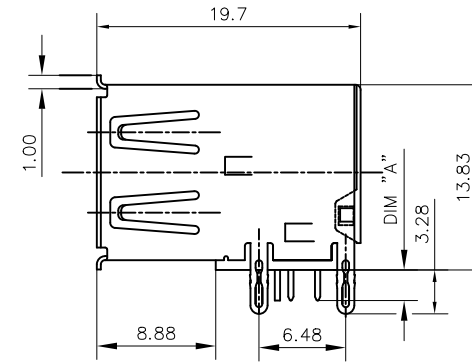
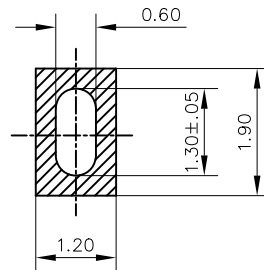


mat'l. code				surface ¹²³ /tolerance ISO 1302 ✓ ISO 406 ISO 1101			projection 		product family HPL 511 USB 2.0			
ltr	ecn no	dr	date	tolerances unless otherwise specified					title USB UP-RIGHT RECEPT			
AJ				angles linear		.0±.30	mm 					
						.00±.20						
				0°±2'		.000±.10						
				dr	PAMP	5/20/97	Amphenol FCI		dwg no		sheet3 of 4	size
				engr	R Y LIU	5/20/97			73725		A3	
				chr	R Y LIU	5/20/97						
				appd	JENN TSAO	5/20/97						
sheet index	revision sheet						type Product Customer Drawing					

PRODUCT NO.
73725



PC BOARD MOUNTING DIMENSIONS FOR 4 PIN



WITHOUT SENSOR CONTACT
FOR 73725-X150B
HOLD DOWN STYLE "C"

mat'l. code				surface	123	tolerance	projection	product family			
				ISO 1302	✓	ISO 406	ISO 1101	HPL 511 USB 2.0			
ltr	ecn no	dr	date	tolerances unless otherwise specified				title			
AJ				angles		.0±.30	mm	USB UP-RIGHT RECEPT			
				linear		.00±.20					
				0°±2°		.000±.10	scale 1:1				
				dr	PAMP	5/20/97	Amphenol FCI	dwg no		sheet 4 of 4	size
				engr	R Y LIU	5/20/97		73725			A3
				chr	R Y LIU	5/20/97					
				appd	JENN TSAO	5/20/97		type Product Customer Drawing			
sheet index	revision sheet										